



## Product Specification

Product:	<b>Dielectric Paste</b>
Part Number:	<b>56M-1809</b>

### Application Scope :

This paste is suitable for encapsulating substrates such as glass-ceramics. It can be applied by printing or coating, features a low sintering temperature, and after firing can withstand temperatures up to 1000°C without performance degradation.

### Usage Conditions :

Substrate	Glass ceramic
Usage Method	Printing, 150-200 mesh
Leveling	Let it level at room temperature for 5-10 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (the test temperature should not exceed 300°C; the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering is carried out in the atmosphere of the furnace tunnel, the peak temperature is 500°C (recommended value), and the time is 10 minutes.
Thinner	

### Characteristics :

#### 1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	≤8μm	FOG test
2 Viscosity	100~200Pa.s	Boli Fei viscometer, rotor SC4-14/6R), 10 rpm, 25±1°C
3 Appearance	<b>Grayish-black</b>	

**2. Characteristics After Curing :**

Under the first sintering condition, the film thickness is no less than 80 $\mu$ m.

Characteristics		Standard	Test Method And Conditions
4	Appearance	Compact and dense	Visual
5	Capacitance of unit	$\leq 3.0\text{PF/mm}^2$	KT2618 type
6	Wastage of insulation	$< 1\%$	KT2618 type
7	Insulation Resistance	$> 10^6\Omega$ (500VDC, 25°C)	RCJ-3 type
8	Breakdown Voltage	$> 500\text{VAC}$ , 25°C	CS2673A type
9	Dielectric Constant( $\epsilon$ )	9~15	Calculation

**Save Conditions And Validity Period :**

The product shall be stored in a sealed container at an ambient temperature of 5-15°C, with a shelf life of 1 year from the date of shipment.

**Packaging Method :**

Standard packaging, 1000g/can; samples are available in 200g small can packaging.